TITLE:

SUBSTRATE PROCESSING APPARATUS AND NON-TRANSITORY COMPUTER READABLE MEDIUM

ABSTRACT

A control device of a substrate processing apparatus is configured to execute: calculating patterns for changing an order of loading to the substrate processing apparatus for multiple substrates loaded to the substrate processing apparatus; generating, for each obtained pattern, a time table in which process end times in the polishing device, the cleaning device, and the transport device are associated, so that an idling state does not occur from a time when the substrates are loaded to the substrate processing apparatus until a cleaning process ends; selecting a time table with a shortest time from a time when a process of a substrate initially loaded to the substrate processing apparatus starts until a process of a lastly loaded substrate ends in the obtained time tables; and controlling timings of loading the substrates to the substrate processing apparatus based on the selected time table.

[FIG. 7]